



Material Content Data Sheet



Halogen-Free

Sales Product Name	TLE5501 E0001	Issued	23. June 2021
MA#	MA005432958		
Package	PG-DSO-8-16	Weight*	82.86 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.430	0.52	0.52	5191	5191
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.036	0.04		433	
	non noble metal	iron	7439-89-6	0.717	0.87		8655	
	non noble metal	copper	7440-50-8	29.121	35.14	36.06	351449	360645
wire	noble metal	gold	7440-57-5	0.177	0.21	0.21	2139	2139
encapsulation	organic material	carbon black	1333-86-4	0.101	0.12		1213	
	plastics	epoxy resin	-	4.624	5.58		55807	
	inorganic material	silicondioxide	60676-86-0	45.538	54.98	60.68	549582	606602
leadfinish	non noble metal	tin	7440-31-5	0.814	0.98	0.98	9822	9822
plating	noble metal	silver	7440-22-4	0.650	0.78	0.78	7848	7848
glue	plastics	epoxy resin	-	0.161	0.19		1938	
	noble metal	silver	7440-22-4	0.482	0.58	0.77	5815	7753
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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